

SEMICONDUCTOR PACKAGE

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ABSTRACT OF THE DISCLOSURE

A semiconductor package is disclosed that bonds a semiconductor chip to a
10 leadframe using a flip chip technology. An exemplary semiconductor package
includes a semiconductor chip having a plurality of input-output pads at an active
surface thereof. A plurality of leads are superimposed by the bond pads and active
surface of the semiconductor chip. The leads have at least one exposed surface at a
bottom surface of the package body. A plurality of conductive connecting means
15 electrically connect the input-output pads of the chip to the leads. A package body
is formed over the semiconductor chip and the conductive connecting means. The
bottom surface portions of the leads are exposed to the outside.